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Specification for 1.3"EPD

Model NO.: HINK-E013A34

Product VER: A0

Customer Approval

Customer	
Approval By	
Date Of Approval	

It will be agreed by the receiver, if not sign back the Specification within 15days.

Prepared By	Checked By	Approval By
王曉斌	文海	王浩



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Version	Content	Date	Producer
A0	New release	2025/9/26	WXB



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1. General Description

HINK- E013A34 is an Active Matrix Electrophoretic Display (AMEPD), with interface and a reference system design. The 1.3" active area contains 144×200 pixels, and has 2-bit B/W/R/Y full display capabilities. An integrated circuit contains gate buffer, source buffer, interface, timing control logic, oscillator, DC-DC, SRAM, LUT, VCOM and border are supplied with each panel.

2. Features

- 144*200 pixels display
- High contrast
- High reflectance
- Ultra wide viewing angle
- Ultra low power consumption
- Pure reflective mode
- Bi-stable display
- Commercial temperature range
- Landscape, portrait modes
- Hard-coat antiglare display surface
- Ultra Low current deep sleep mode
- On chip display RAM
- Low voltage detect for supply voltage
- High voltage ready detect for driving voltage
- Internal temperature sensor
- Waveform stored in On-chip OTP
- Serial peripheral interface available
- On-chip oscillator
- On-chip booster and regulator control for generating VCOM, Gate and Source driving voltage
- I2C signal master interface to read external temperature sensor/ built-in temperature sensor

3. Application

Electronic Shelf Label System



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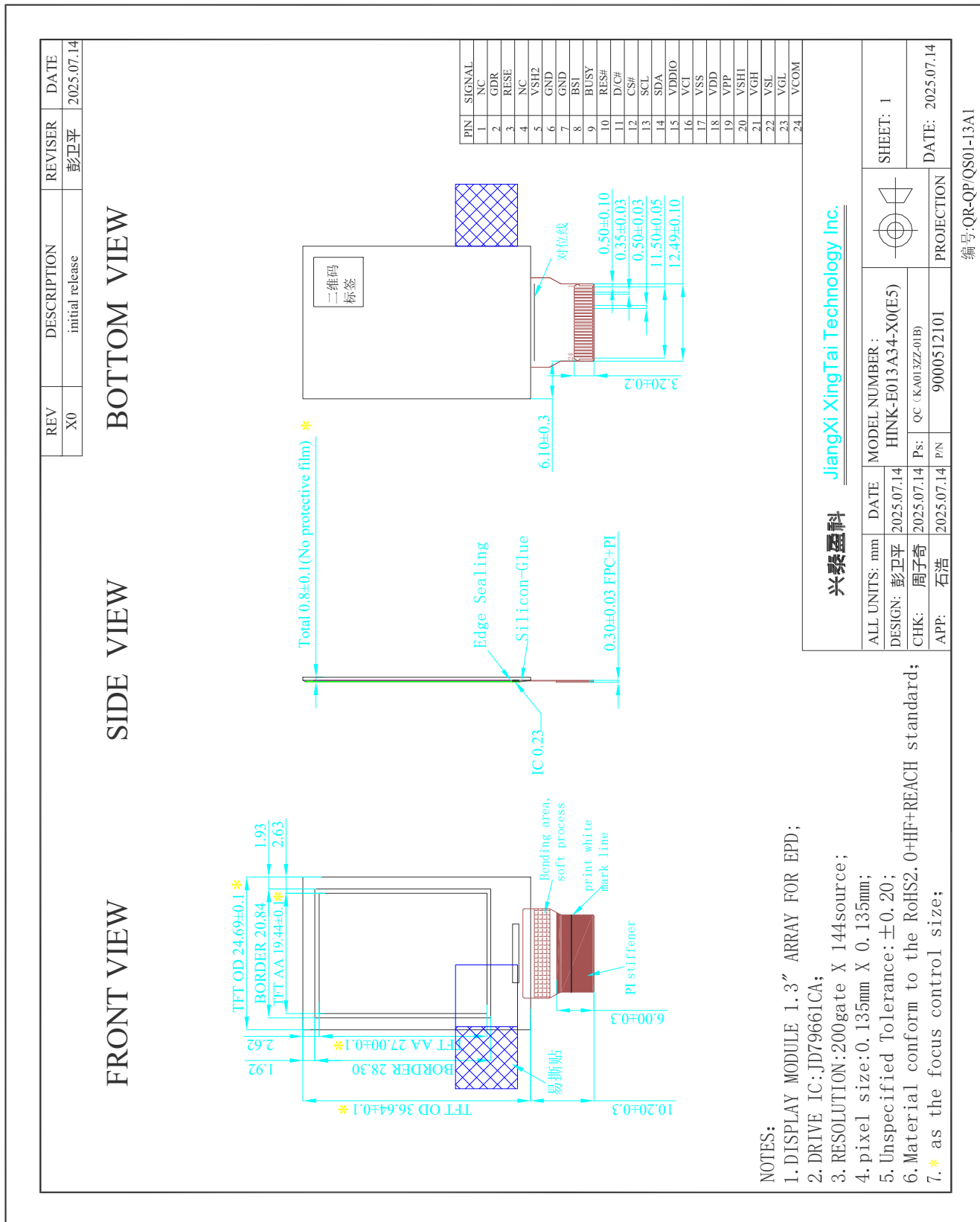
4. Mechanical Specifications

Parameter	Specifications	Unit	Remark
Screen Size	1.3	Inch	
Display Resolution	144(H)×200(V)	Pixel	Dpi:188
Active Area	19.44(H)×27.00(V)	mm	
Pixel Pitch	0.135×0.135	mm	
Pixel Configuration	Rectangle		
Outline Dimension	24.69(H)×36.64(V) ×0.8(D)	mm	Without masking film
FPL Type	E5黑白红黄四色		
IC	JD79661CA		
Weight	1.77±0.5	g	



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5. Mechanical Drawing of EPD module





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6. Input/output Terminals

Pin #	Single	Description	Remark
1	NC	No connection and do not connect with other NC pins	Keep Open
2	GDR	N-Channel MOSFET Gate Drive Control	
3	RESE	Current Sense Input for the Control Loop	
4	NC	No connection and do not connect with other NC pins e	Keep Open
5	VSH2	This pin is Positive Source driving voltage	
6	GND		GND
7	GND		GND
8	BS1	Bus selection pin	Note 6-5
9	BUSY	Busy state output pin	Note 6-4
10	RES #	Reset	Note 6-3
11	D/C #	Data /Command control pin	Note 6-2
12	CS #	Chip Select input pin	Note 6-1
13	SCL	serial clock pin (SPI)	
14	SDA	serial data pin (SPI)	
15	VDDIO	Power for interface logic pins	
16	VCI	Power Supply pin for the chip	
17	VSS	Ground	
18	VDD	Core logic power pin	
19	VPP	Power Supply for OTP Programming	
20	VSH1	This pin is Positive Source driving voltage	
21	VGH	This pin is Positive Gate driving voltage	
22	VSL	This pin is Negative Source driving voltage	
23	VGL	This pin is Negative Gate driving voltage	
24	VCOM	These pins are VCOM driving voltage	



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1. Note 6-1: This pin (CSB) is the chip select input connecting to the MCU. The chip is enabled for MCU communication: only when CSB is pulled LOW.
2. Note 6-2: This pin (DC) is Data/Command control pin connecting to the MCU. When the pin is pulled HIGH, the data will be interpreted as data. When the pin is pulled LOW, the data will be interpreted as command.
3. Note 6-3: This pin (RST_N) is reset signal input. The Reset is active low.
4. Note 6-4: This pin (BUSY_N) is busy state output pin. When Busy is Low, the operation of chip should not be interrupted and any commands should not be issued to the module. The driver IC will put Busy pin High when the driver IC is working such as: Outputting display waveform; Communicating with digital temperature sensor
5. Note 6-5: This pin (BS) is for 3-line SPI or 4-line SPI selection. When it is "Low", 4-line SPI is selected. When it is "High", 3-line SPI (9 bits SPI) is selected.
- 6: We had made Pin 6 and Pin 7 on FPC to be ground.



The diagram illustrates a 24-pin connector with the following pin assignments and connections:

- Pin 1:** NC (No Connection)
- Pin 2:** GDR
- Pin 3:** RESE
- Pin 4:** NC
- Pin 5:** VSH2
- Pin 6:** NC
- Pin 7:** NC
- Pin 8:** BS
- Pin 9:** BUSY
- Pin 10:** BUSY_N
- Pin 11:** RST_N
- Pin 12:** DC
- Pin 13:** CSB
- Pin 14:** SCL
- Pin 15:** SDA
- Pin 16:** VDDIO
- Pin 17:** VCC
- Pin 18:** VSS
- Pin 19:** VDD
- Pin 20:** VPP
- Pin 21:** VSH1
- Pin 22:** VGH
- Pin 23:** VSL
- Pin 24:** VGL
- Pin 25:** VCOM

Component connections shown in the diagram:

- Capacitors:** C7, C8, C9, C10 are connected to ground (pin 18).
- Resistors:** R1, R9 are connected between pins 13 and 14.
- Other connections:** Pin 17 (VCC) is connected to pin 16 (VDDIO) and pin 15 (SDA). Pin 15 (SDA) is also connected to pin 14 (SCL).

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 表单编号: QR-RD(HINK)021-31A1



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Part Name	Value /requirement/Reference Part
C1—C9	1uF/0603;X5R/X7R;Voltage Rating: 25V
C10	1uF/0603;X7R;Voltage Rating: 25V
D1—D3	MBR0530 1) Reverse DC voltage $\geq 30V$ 2) Forward current $\geq 500mA$ 3) Forward voltage $\leq 430mV$
R2	2.2 Ω /0603: 1% variation
Q1	NMOS:Si1304BDL/NX3008NBK 1) Drain-Source breakdown voltage $\geq 30V$ 2) $V_{gs(th)} = 0.9 (Typ), 1.3V (Max)$ 3) $R_{ds on} \leq 2.1\Omega @ V_{gs}=2.5V$
L1	47uH/CDRH2D18、LDNP-470NC Maximum DC current~420mA Maximum DC resistance~650m Ω
CON24Pin	0.5mm ZIF Socket 26Pins,0.5mm pitch



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8. ABSOLUTE MAXIMUM RATING

Parameter	Symbol	Rating	Unit	Humidity	Unit	Note
Logic Supply voltage	VCC,VDDIO	-0.5~6.0	V	45~70	%RH	Note 8-1
Operation temperature range	TOPR	0~40	°C	45~70	%RH	
Storage temperature range	TSTG	-25~50	°C	45~70	%RH	Note 8-2
Transportation temperature range	TTTG	-25~50	°C	45~70	%RH	Note 8-3
GND	Ground	-	-		-	Connect to Ground

Note 8-1: Maximum ratings are those values beyond which damages to the device may occur. VCC: Digital power, VDDIO: IO power. Functional operation should be restricted to the limits in the Electrical Characteristics chapter.

Note 8-2: The display effect may be affected if the product is stored for more than 10days under the environment of 40-60 degree.

Note 8-3: TTTG is the transportation condition, the transport time is within 10 days for 40°C~60°C

Note 8-4: The single pixel effect under the condition of above 35 degree cannot be guaranteed , Normal use is recommended to refresh every 24 hours;

Note 8-5: Due to the nature of FPL,we will not control the display effect of white characters on yellow and yellow characters on white.

9. DC Characteristics

The following specifications apply for: VSS=0V, VDD=3.3V, TOPR=25°C

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Unit
VDD	VDD operation voltage	-	2.4	3.3	3.6	V
VIH	High level input voltage	-	0.7xVIO	-	VIO	V
VIL	Low level input voltage	-	GND	-	0.3xVDD	V
VOH	High level output voltage	IOH = 400μA	VIO-0.4	-	-	V
VOL	Low level output voltage	IOL = -400μA	GND	-	GND+0.4	V
Iupdate	Module operating current	-	-	3	-	mA
Isleep	Deep sleep mode	VCI=3.3V	-	-	3	uA

- The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by XingTai.

- VCOM value will be OTP before in factory.

These currents are tested with Xingtai testing jig



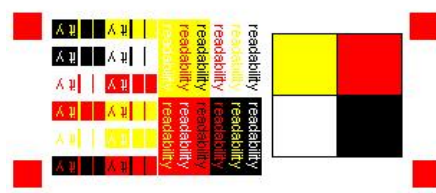
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10. Power Consumption

Parameter	Symbol	Conditions	TYP	Max	Unit	Remark
Panel power consumption during update	-	25°C		60	mAs	-

MAs=update Average current ×update time

The Typical power consumption is measured using associated 25°C waveform with following pattern:



11. Optical characteristics

11.1 Optical Measurement Conditions

Item	Symbol	Value	Unit	Note
Ambient Temperature	Ta	25±2	°C	Indoor testing
Ambient Humidity	Ha	50±5	%RH	-
Supply Voltage	VCC, VDDIO	3.0	V	-
illuminance	-	800~1300	Lux	

Note 11-1: Image is updated with above condition

11.2 Optical Measurement

WS: White state, BS: Black state, RS: Red state, YS: Yellow State

Note 11-2: Luminance meter: Eye - One Pro Spectrophotometer

Note 11-3: We don't guarantee 5 years pixels display quality for humidity below 45%RH or above 70%RH; Suggest Updated once a day;

Note 11-4: To increase the black and white screen clear screen when red and yellow has refreshed for a long time, the effect is better.

Note 11-5: Due to the poor consistency, the white text of 1x1 dot in the yellow background and the yellow text of 1x1 dot in the white background cannot be guaranteed in terms of display effect.



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WS : White state, KS : Black State,

T=25°C ,VDD=3.3V

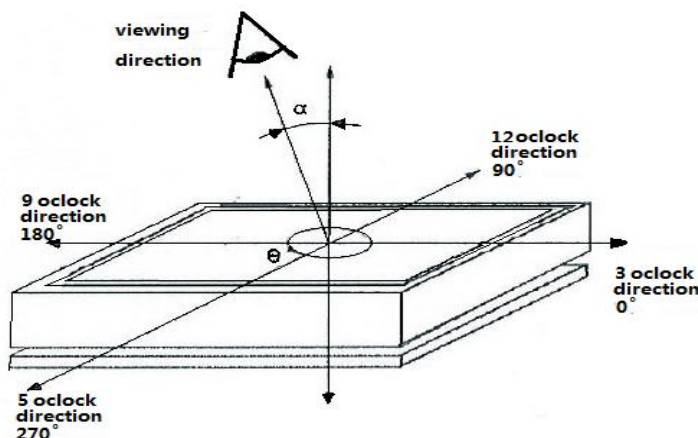
SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT	Note
R	Reflectance	White	30	35	-	%	Note 11-3
Gn	2Grey Level	-	-	$KS+(WS-KS) \times n(m-1)$	-	L*	-
CR	Contrast Ratio	-	-	10	-	-	-
KS	Black State L* value	-	-	9	14	-	Note 11-3
	Black State a* value	-	-	-	8	-	Note 11-3
	Black State b* value	-	-	0.5	2	-	Note 11-3
WS	White State L* value	-	60	65	-	-	Note 11-3
	White State a* value	-	-	0	1	-	Note 11-3
	White State b* value	-	-	-	4	-	Note 11-3
RS	Red State L* value	Red	23	25	29	-	Note 11-3
	Red State a* value	Red	37	40	-	-	Note 11-3
	Red State b* value	Red	-	-	35	-	Note 11-3
YS	Yellow State L* value	Yellow	56	61	66	-	Note 11-3
	Yellow State a* value	Yellow	-	-	20	-	Note 11-3
	Yellow State b* value	Yellow	59	68	-	-	Note 11-3
Panel	Image Update	Storage and transportation	-	Update the white screen	-	-	-
	Update Time	Operation	-	Suggest Updated once a day	-	-	-

11.3 Reflection Ratio

The reflection ratio is expressed as:

$R = \text{Reflectance Factor white board} \times (L_{\text{center}} / L_{\text{white board}})$

L center is the luminance measured at center in a white area (R=G=B=1). L white board is the luminance of a standard white board. Both are measured with equivalent illumination source. The viewing angle shall be no more than 10 degrees.





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12. Handling Safety and Environmental Requirements

WARNING

The display module should be kept flat or fixed to a rigid, curved support with limited bending along the long axis. It should not be used for continual flexing and bending. Handle with care. Should the display break do not touch any material that leaks out. In case of contact with the leaked material then wash with water and soap.

CAUTION

The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components.

Disassembling the display module can cause permanent damage and invalidate the warranty agreements.

IPA solvent can only be applied on active area and the back of a glass. For the rest part, it is not allowed.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricity and other rough environmental conditions.

Mounting Precautions

(1) It's recommended that you consider the mounting structure so that uneven force (ex. Twisted stress) is not applied to the module.

(2) It's recommended that you attach a transparent protective plate to the surface in order to protect the EPD. Transparent protective plate should have sufficient strength in order to resist external force.

(3) You should adopt radiation structure to satisfy the temperature specification.

(4) Acetic acid type and chlorine type materials for the cover case are not desirable because the former generates corrosive gas of attacking the PS at high temperature and the latter causes circuit break by electro-chemical reaction.

(5) Do not touch, push or rub the exposed PS with glass, tweezers or anything harder than HB pencil lead. And please do not rub with dust clothes with chemical treatment. Do not touch the surface of PS for bare hand or greasy cloth. (Some cosmetics deteriorate the PS)

(6) When the surface becomes dusty, please wipe gently with absorbent cotton or other soft materials like chamois soaks with petroleum benzene. Normal-hexane is recommended for cleaning the adhesives used to attach the PS. Do not use acetone, toluene and alcohol because they cause chemical damage to the PS.

(7) Wipe off saliva or water drops as soon as possible. Their long time contact with PS causes deformations and color fading.



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Data sheet status	
Product specification	The data sheet contains final product specifications.

Limiting values
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.
Application information
Where application information is given, it is advisory and dose not form part of the specification.

Product Environmental certification
ROHS
REMARK
All The specifications listed in this document are guaranteed for module only. Post-assembled operation or component(s) may impact module performance or cause unexpected effect or damage and therefore listed specifications is not warranted after any Post-assembled operation.



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13. Reliability test

13.1 Reliability test items

	TEST	CONDITION	METHOD	REMARK
1	High-Temperature Operation	T=40°C, RH=35%RH, For 240Hr		
2	Low-Temperature Operation	T = 0°C for 240 hrs		
3	High-Temperature Storage	T=50°C RH=35%RH For 240Hr Test in white pattern		
4	Low-Temperature Storage	T = -25°C for 240 hrs Test in white pattern		
5	High Temperature, High-Humidity Operation	T=40°C, RH=90%RH, For 168Hr		
6	High Temperature, High-Humidity Storage	T=50°C, RH=90%RH, For 240Hr Test in white pattern		
7	Temperature Cycle	-25°C(30min)~60°C(30min), 50 Cycle Test in white pattern		
8	Package Vibration	1.04G,Frequency : 20~200Hz Direction : X,Y,Z Duration:1hours in each direction	Full packed for shipment	
9	Package Drop Impact	Drop from height of 100 cm on Concrete surface Drop sequence:1 corner, 3edges, 6face One drop for each.	Full packed for shipment	
10	UV exposure Resistance	765 W/m ² for 168hrs,40°C		
11	Electrostatic Effect(non-operating)	Machine model: +/-250V,0Ω,200pF		

Actual EMC level to be measured on customer application.

Note1: Stay white pattern for storage and non-operation test.

Note2: Power off duration time is 150s

Note3: Continue testing after 2 hours at 20C~25C°C

13.2 Product life time

The EPD Module is designed for a 5-year life-time with 25 °C/60%RH operation assumption. Reliability estimation testing with accelerated life-time theory would be demonstrated to provide confidence of EPD lifetime.

13.3 Product warranty

Warranty conditions have to be negotiated between Xingtai and individual customers.

Xingtai provides 12+1(one month delivery time) months warranty for all products which are purchased from Xingtai.

Actual EMC level to be measured on customer application.

Note1: Stay white pattern for storage and non-operation test.

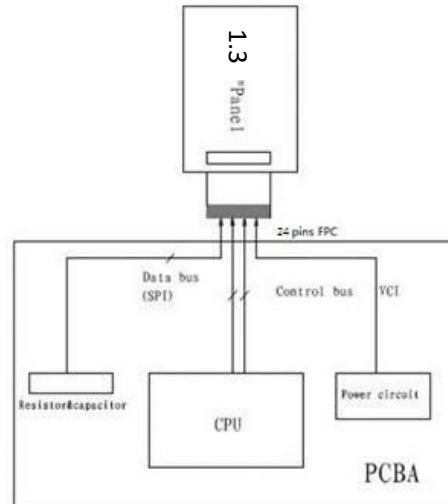
Note2: Power off duration time is 30s

Note3: Continue testing after 2 hours at 20C~25C”



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14. Block Diagram



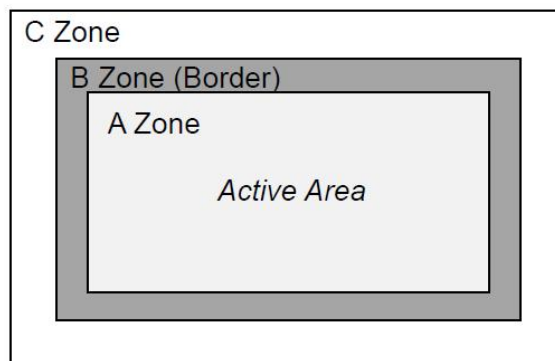
15. Shipment inspection specification

15.1 Zone Definition

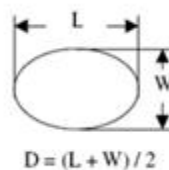
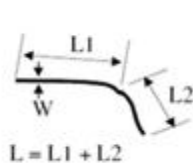
A Zone: Active Area

B Zone: Border Area

C Zone: From B Zone edge to panel edge



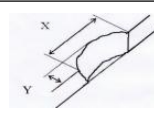
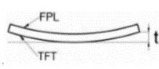
15.2 Line/Spot defect size





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15.3. Point and line standard

Shipment Inspection Standard						
Equipment: Electrical test fixture, Point gauge						
Outline dimension	24.69(H)× 36.64(V) × 0.8(D)	Unit: mm	Part-A	Active area	Part-B	Border area
Environment	Temperature	Humidity	illuminance	Distance	Time	Angle
	19℃~25℃	50±5%RH	800~1300Lux	300 mm	35Sec	45°
Defect type	Inspection method	Standard		Part-A	Part-B	
Spot	Electric Display	D≤0.25 mm		Ignore	Ignore	
		0.25 mm<D≤0.4 mm		N≤4	Ignore	
		D>0.4 mm		Not Allow	Ignore	
Display malfunction	Electric Display	Not Allow		Not Allow	Ignore	
Display error	Electric Display	Not Allow		Not Allow	Ignore	
Scratch or line defect(include dirt)	Visual/Film card	L≤2 mm,W≤0.2 mm		Ignore	Ignore	
		2.0mm<L≤5.0mm,0.2<W≤0.3mm,		N≤2	Ignore	
		L>5 mm,W>0.3 mm		Not Allow	Ignore	
PS Bubble	Visual/Film card	D≤0.2mm		Ignore	Ignore	
		0.2mm≤D≤0.35mm		N≤4	Ignore	
		D>0.35 mm		Not Allow	Ignore	
Corner /Edge chipping	Visual/Film card	X≤6mm,Y≤0.4mm, Do not affect the electrode circuit (Edge chipping)				
		X≤1mm,Y≤1mm, Do not affect the electrode circuit((Corner chipping) Ignore				
		 				
TFT warping	For 1.54~7.5inch, T≤2mm; For above 7.5inch, T≤3mm					
Remark	1.Cannot be defect & failure cause by appearance defect;					
	2.Cannot be larger size cause by appearance defect;					
	L=long W=wide D=point size N=Defects NO					



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15.4 Barcode



What is the QR code after picture being scanned and read? It consist of 30 numbers and letters, here is explanation for it.

QR Code: ABBBBBBBBBBFFCCDDDEEEEGHIJKLL

- ① A means Factory code, e.g.: H (HINK)
- ② BBBBBBBBBB refers to product model name, which is in consistent with specification part number. E.g.: E0213A189 or E0266A120; when the total code is less than 9, it would be added suffix with **. e.g.: E027A45** or E0154A78*
- ③ FF means production workshop
- ④ CCC means date of production
- ⑤ DDD means production batch
- ⑥ EEEE means FPL lot
- ⑦ G means MP/Sample/Trial/Repair
- ⑧ HIJ:(H——TFT;I——PS;J——EC Glue)
- ⑨ KK means IC type
- ⑩ LL means serial number



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16. Packing

Full carton: 12 pcs tray with products and 1 pcs empty tray.

Last carton: less 12pcs tray with products and 1 pcs empty tray. The packager will add the right amount of EPE to box so that the added EPE's height approximately close to the EPE height around the inside of the box.

